

JPSA Partners with DynTest Technologies for Wafer Scriber/Breaker Development

Manchester, New Hampshire, USA – J P Sercel Associates (JPSA) announces a collaborative partnership with DynTest Technologies (www.dyntest.de) of Grassau, Germany, to develop and manufacture new high-precision scriber / breaker solutions for wafer singulation. DynTest specializes in highly precise, accurate, and efficient breaking systems that enhance production yields and productivity, while JPSA specializes in high-speed, high-accuracy laser workstations for wafer scribing.



“The combined benefits of highly precise scribing and breaking technologies are the driving forces behind this collaboration” Rick Slagle, Sales and Marketing Director of JPSA, said. “JPSA’s laser scribing systems deliver the narrowest kerf in the industry – 2.5 microns – at high speed, for maximum yields per wafer. DynTest brings advanced, precise breaking expertise to this relationship. The combined technology of JPSA and DynTest Technologies allows thicker material to be singulated accurately, meaning less scribing time, higher throughput and higher yields.”

“This provides the industry new opportunities for traceable device singulation in high volume manufacturing” support Joerg Lindner and Helge Luesebrink, Managing Directors of DynTest Technologies.

“Furthermore, these systems can break very small, relatively thick VCSEL and HB-LED dies” Slagle added. The result of the collaboration will mean excellent process speed and performance with improved yield rates. In addition to the quite sensitive epitaxial material of VCSELs and HB-LEDs, wafers with backside metallization, III-V wafers, ceramic substrates and comparable brittle materials can all be processed with ease.

About J. P. Sercel Associates

JPSA products and services include UV excimer, DPSS and ultra-fast laser micromachining systems, laser beam delivery systems, laser materials processing development, optical damage testing, and excimer laser refurbishment services. JPSA operates a high-performance contract manufacturing facility as well as a systems engineering and manufacturing business. For more information, visit www.jpsalaser.com, or contact the company at 220 Hackett Hill Road, Manchester, NH, 03102 USA; Tel. 603.518.3200, Fax 603.518.3298.

About DynTest Technologies

DynTest Technologies GmbH specializes in Scriber/Breaker solutions for substrates used to manufacture opto, and electronic components, with patented technology for III-V wafers. The product family offers extended process flexibility and repeatability to separate brittle materials with enhanced yield and high throughput. In addition to systems the company provides a dedicated range of consumables for scribing/breaking. More information about DynTest is available at www.dyntest.de, or contact the company at 110 Bahnhofstrasse, 83224 Grassau Germany, Tel. +49 8641 6969-0, Fax +49 8641 6969-29.